



- 1 Substrate: 1.59mm  $\pm$ 0.18mm [0.0625"  $\pm$ 0.007"] FR4/G10 or equivalent high temp material. 17 $\mu$ m [1/2 oz.] Cu clad. SnPb plating.
- 2 Pins: material- Brass Alloy 360 1/2 hard; finish- 0.25 $\mu$ m [10 $\mu$ "] Au over 1.27 $\mu$ m [50 $\mu$ "] Ni (min.).
- 4 Leads: material- BeCu Alloy 194; plating- 60/40 SnPb 3.80-10.16 $\mu$ m [150-400 $\mu$ "].

**Description:** SO surface mount emulator foot

16 position (0.05" pitch) J-led surface mountable emulator foot, with mini grid array (MGA) pin interface. .

Tolerances: diameters  $\pm$ 0.03mm [ $\pm$ 0.001"], PCB perimeters  $\pm$ 0.13mm [ $\pm$ 0.005"], PCB thicknesses  $\pm$ 0.18mm [ $\pm$ 0.007"], pitches (from true position)  $\pm$ 0.08mm [ $\pm$ 0.003"], all other tolerances  $\pm$ 0.13mm [ $\pm$ 0.005"] unless stated otherwise.

<b>SF-SO16B-J-02 Drawing</b>		Status: Released	Scale: 4:1	Rev: C
 <p>© 1997 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com</p>	Drawing: E. Swanson		Date: 4/30/97	
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